



## APPENDIX

## Changes to Claims:

Claims 27-31 are added.

The following are marked-up versions of the amended claims:

1. (Amended) A semiconductor device comprising:

a semiconductor chip on which a plurality of electrodes are formed;

a first flexible substrate on which a wiring pattern is formed and on which the semiconductor chip is mounted;

a plurality of external terminals electrically connected to the electrodes with the wiring pattern interposed; and

a second flexible substrate adhered to the first flexible substrate avoiding the semiconductor chip,

wherein the second flexible substrate is formed of the same material as the first flexible substrate.

2. (Amended) The semiconductor device as defined in claim 1,

wherein the first and second flexible substrates are of ~~the same material and of~~ substantially the same thickness.

4. (Amended) ~~A~~The semiconductor device as defined in claim 3, ~~further~~ comprising:

a semiconductor chip on which a plurality of electrodes are formed;

a first flexible substrate on which a wiring pattern is formed and on which the semiconductor chip is mounted;

a plurality of external terminals electrically connected to the electrodes with the wiring pattern interposed;

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\_\_\_\_\_ a second flexible substrate adhered to the first flexible substrate avoiding the semiconductor chip; and

a conductive layer which is formed between the first and second flexible substrates, of the same material and of substantially the same thickness as the wiring pattern, and is electrically insulated from the wiring pattern.